



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Kuniko Kikuta

Serial No.: 09/584,739

Group Art Unit: 2814

Filed: June 1, 2000

Examiner: Quach, Tuan N.

For: COPPER-ALLOY INTERCONNECTION LAYER

Honorable Commissioner of Patents  
Washington, D.C. 20231

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J. M. M. M.  
4-8-03  
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MAR-5 2003  
TECHNOLOGY CENTER 2800

**AMENDMENT UNDER 37 C.F.R. §1.111**

Sir:

In response to the Office Action dated **December 4, 2002**, please amend the above-identified application as follows:

**IN THE CLAIMS:**

Please cancel claims 3, 5, 13, 14, 26 and 27 without prejudice or disclaimer.

**Please amend the following claims:**

1. (Amended) An electrically conductive layer comprising:

a copper alloy which includes at least one of Ag, As P, Si, Bi, Sb, and Ti at not less than 0.1 percent by weight,

wherein said copper alloy further includes at least one of Mo, Ta and W in a range of not less than 0.1 percent by weight to not more than 1 percent by weight, and

wherein said copper alloy further includes at least one of Cr and Ni in a range of not less than 0.1 percent by weight to not more than 1 percent by weight.